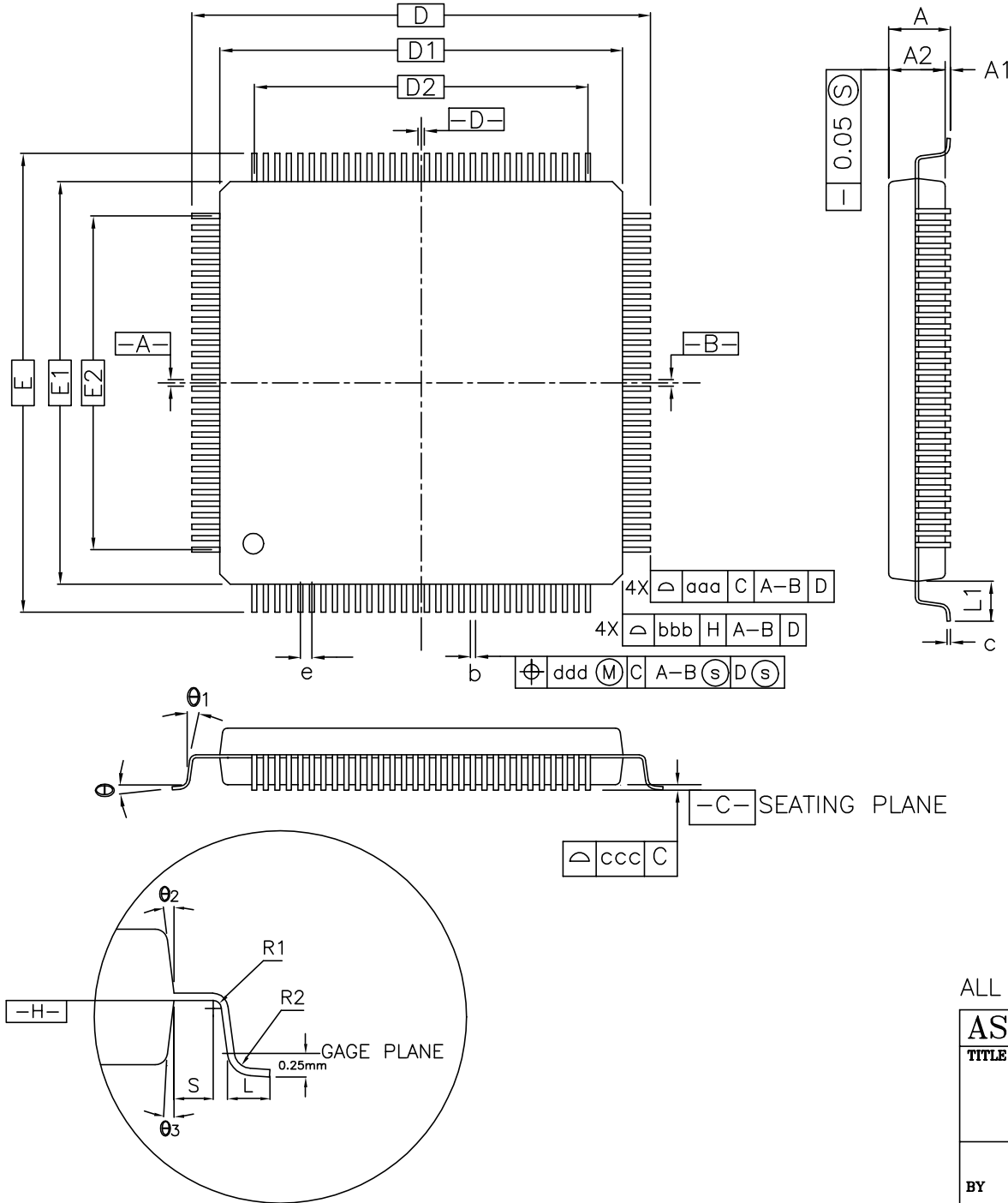


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CONTROL DIMENSIONS ARE IN MM.

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	4.10	—	—	0.161
A1	0.25	—	—	0.010	—	—
A2	3.20	3.32	3.60	0.126	0.131	0.142
D	30.60 BSC.			1.205 BSC.		
D1	28.00 BSC.			1.102 BSC.		
E	30.60 BSC.			1.205 BSC.		
E1	28.00 BSC.			1.102 BSC.		
R2	0.08	—	0.25	0.003	—	0.010
R1	0.08	—	—	0.003	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	—	—	0°	—	—
θ_2	8° REF			8° REF		
θ_3	8° REF			8° REF		
c	0.09	0.15	0.20	0.004	0.006	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L ₁	1.30 REF			0.051 REF		
S	0.20	—	—	0.008	—	—

ALL DIMENSION IN MM

ASE ADVANCED SEMICONDUCTOR ENGINEERING, INC.		ASE ELECTRONICS (M) SDN BHD		DWG. NO.	REV.
TITLE		PACKAGE OUTLINE		84-06-112-007	ORIG.
		QFP 208/256L		SHEET	
		28x28x3.32 mm		1 OF 3	
		2.6mm FOOTPRINT		SIZE	
				A4	
BY	DRAWN	CHECKED	APPROVED	ACAD FILE	REF JEDEC NO
	HS LAM	RAYMOND	TT TOONG	D6112007	MO-143

SYMBOL	208L						256L					
	MILLIMETER			INCH			MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
b	0.17	0.20	0.27	0.007	0.008	0.011	0.13	0.16	0.23	0.005	0.006	0.009
e	0.50 BSC.			0.020 BSC.			0.40 BSC.			0.016 BSC.		
D2	25.50			1.004			25.20			0.992		
E2	25.50			1.004			25.20			0.992		
TOLERANCES OF FORM AND POSITION												
aaa	0.20			0.008			0.20			0.008		
bbb	0.20			0.008			0.20			0.008		
ccc	—	0.08	—	—	0.003	—	—	0.08	—	—	0.003	—
ddd	—	0.08	—	—	0.003	—	—	0.07	—	—	0.003	—

NOTES :

- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM b DIMENSION BY MORE THAN 0.08mm.
DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. THE MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.
- THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE BODY SIZE.

ASE <small>ADVANCED SEMICONDUCTOR ENGINEERING, INC.</small> ASE ELECTRONICS (M) SDN BHD		DWG. NO.		REV.	
		84-06-112-007		ORIG.	
TITLE PACKAGE OUTLINE QFP 208/256L 28x28x3.32 mm 2.6mm FOOTPRINT		SHEET		SIZE	
		2 OF 3		A4	
BY	DRAWN	CHECKED	APPROVED	ACAD FILE	REF JEDEC NO
	HS LAM	RAYMOND	TT TOONG	D6112007	MO-143

REVISION HISTORY :

REV.	DESCRIPTION OF CHANGE	DATE
ORIG.	INITIAL RELEASE (REGENERATE DRAWING FROM SPEC # 84-06-100-007 REV C)	10/24/01

ASE	<small>ADVANCED SEMICONDUCTOR ENGINEERING, INC.</small>	ASE ELECTRONICS (M) SDN BHD	DWG. NO.	REV.	
TITLE PACKAGE OUTLINE QFP 208/256L 28x28x3.32 mm 2.6mm FOOTPRINT		84-06-112-007	ORIG.		
		SHEET	SIZE		
		3 OF 3	A4		
	DRAWN	CHECKED	APPROVED	ACAD FILE	REF JEDEC NO
BY	HS LAM	RAYMOND	TT TOONG	D6112007	M0-143
DATE					